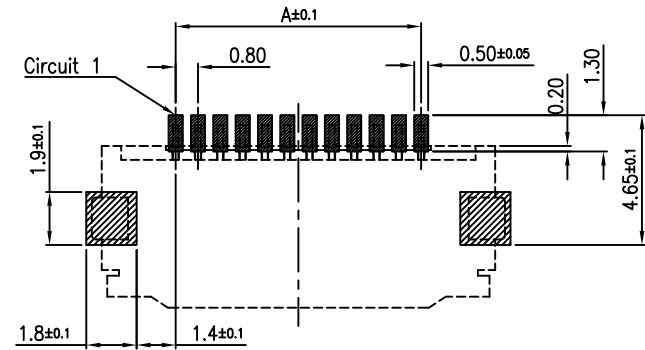
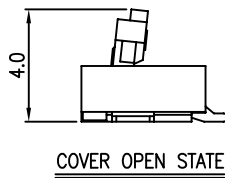
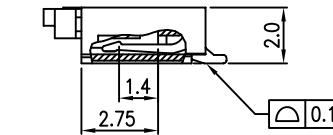
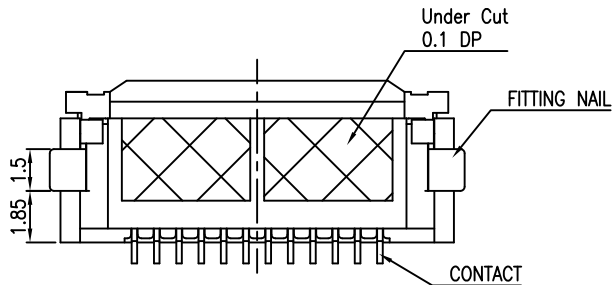
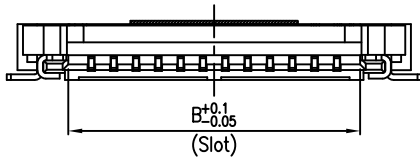


APPLICABLE FPC
RECOMMENDED DIM.
(THICKNESS: 0.3±0.03)



RECOMMENDED PC BOARD
PATTERN DIM. (REF.)



NOTES:

1. MATERIAL:
 - 1.1 HOUSING: THERMOPLASTIC, HIGH TEMP., UL94V-0; COLOR:NATURAL.
 - 1.2 HOUSING: THERMOPLASTIC, HIGH TEMP., UL94V-0; COLOR:BLACK.
 - 1.3 CONTACT: COPPER ALLOY
 - 1.4 FITTING NAIL: COPPER ALLOY
2. FINISH:
 - 2.1 CONTACT:
 - UNDER PLATING: 50~100u" MIN. NICKEL OVERALL
 - FINISH:SEE ORDER INFORMATION.
 - 2.2 FITTING NAIL:
 - UNDER PLATING: 50~100u" MIN. NICKEL OVERALL
 - FINISH:SEE ORDER INFORMATION.
3. REFLOW SOLDER CAPABLE TO 260°C

CKT	Dim A	Dim B	Dim C	M/S(W)
4	2.40	4.06	7.7	6.0
5	3.20	4.86	8.5	6.0
6	4.00	5.66	9.3	6.0
7	4.80	6.46	10.1	6.0
8	5.60	7.26	10.9	6.0
9	6.40	8.06	11.7	6.0
10	7.20	8.86	12.5	6.0
11	8.00	9.66	13.3	6.0
12	8.80	10.46	14.1	6.0
13	9.60	11.26	14.9	6.0
14	10.40	12.06	15.7	10.0
15	11.20	12.86	16.5	10.0
16	12.00	13.66	17.3	10.0
17	12.80	14.46	18.1	10.0
18	13.60	15.26	18.9	10.0
19	14.40	16.06	19.7	10.0
20	15.20	16.86	20.5	10.0
21	16.00	17.66	21.3	10.0
22	16.80	18.46	22.1	15.0
23	17.60	19.26	22.9	15.0
24	18.40	20.06	23.7	15.0
25	19.20	20.86	24.5	15.0
26	20.00	21.66	25.3	15.0
27	20.80	22.46	26.1	15.0
28	21.60	23.26	26.9	15.0
29	22.40	24.06	27.7	15.0
30	23.20	24.86	28.5	15.0
31	24.00	25.66	29.3	15.0
32	24.80	26.46	30.1	15.0
33	25.60	27.26	30.9	15.0
34	26.40	28.06	31.7	15.0
35	27.20	28.86	32.5	15.0
36	28.00	29.66	33.3	15.0
37	28.80	30.46	34.1	15.0
38	29.60	31.26	34.9	15.0
39	30.40	32.06	35.7	15.0
40	31.20	32.86	36.5	15.0

FPE-WHB-xx-LF
LEADFREE
04~40WAY
RoHS Compliant

	PART NO. FPE-WHB-xx		CHECKED BY CY	TOLERANCES ARE .X ± 0.2 .XX ± .XXX ± AWG	DESCRIP TION: 0.8 PITCH EASY ON FPC CONN. SMT R A B C TYPE		
	DWG NO. FPE-WHB-xx					DRAWING BY	
	FILE NO.		PROJECTION	AREA	REVISIONS	HK	DATE
	UNIT / mm	SCALE 1:1					